BS IEC 63011-1:2018

BSI Standards Publication

Integrated circuits – Three dimensional integrated circuits

Part 1: Terminology

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National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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INTEGRATED CIRCUITS – THREE DIMENSIONAL INTEGRATED CIRCUITS –

Part 1: Terminology

FOREWORD

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International Standard IEC 63011-1 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47A/1060/FDIS	47A/1064/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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